

ESPI Current Report

Number: 7/2023

Date of preparation: 10 March 2023

Company: XTPL S.A., a joint stock company with its registered office in Wrocław

Title:

The approval of a patent by the Intellectual Property Corporation Of Malaysia

Legal basis: Article 17(1) MAR – inside information

Contents of the Report:

The Management Board of XTPL ("Issuer", "Company", "XTPL") hereby reports that on March 8th, 2023 it received information about the approval of a patent by the Intellectual Property Corporation Of Malaysia for the method of forming lines with a width below 1 micrometer using the XTPL-developed ink containing nanoparticles of silver. The patent was granted in response to the patent application "Bottom-up method for forming wire structures upon a substrate".

The application procedure for this patent was initiated on March 22nd, 2016. This is also the date when patent protection started for the invention. The Company's portfolio currently includes 26 patent applications and a total of 3 patents granted.

The patent protection will increase the value of the potential commercialization of the Company's technology with respect to the Issuer's technological solutions for the next-generation electronics market. The reported event confirms the continued delivery of the Company's strategy of building a patent cloud for its proprietary technology and products, which will contribute to building the Issuer's credibility among potential industrial clients.

In view of the above, and considering the confirmation of uniqueness of the Company's technological solutions, and then the outlook for the Issuer's perception by investors, the Issuer's Management Board has decided that the conditional decision to grant the patent to the Company should be deemed inside information. For this reason, in the opinion of the Management Board, the information meets the criteria set out in Article 7(1) of the MAR.

Signatures of Company's representatives:

Jacek Olszański MANAGEMENT BOARD MEMBER